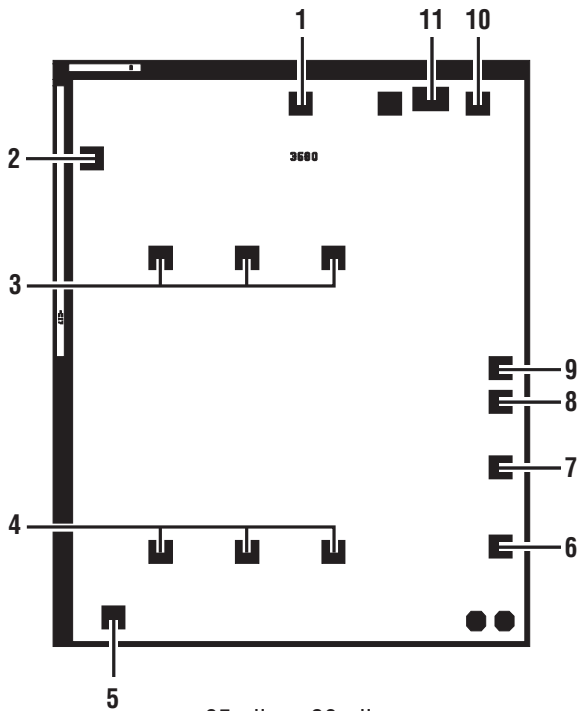


LT3680

36V, 3.5A, 2.4MHz Step-Down Switching
Regulator with 75µA Quiescent Current



65mils × 80mils,
?mils thick.
Backside metal: ?
Backside potential: ?

PAD FUNCTION

1. BD
2. BOOST
3. SW
4. V_{IN}
5. RUN/SS
6. SYNC
7. PG
8. FB
9. V_C
10. RT
11. GND

DIE CROSS REFERENCE

LT® Finished Part Number	Order Part Number
LT [®] 3680 LT3680	LT3680DICE LT3680DWF*

Please refer to ADI standard product data sheet for other applicable product information.

*DWF = DICE in wafer form.

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ABSOLUTE MAXIMUM RATINGS

(Note 1)

V_{IN} , RUN/SS Voltage.....	36V
BOOST Pin Voltage	56V
BOOST Pin Above SW Pin.....	30V
FB, RT, V_C Voltage	5V
PG, BD, SYNC Voltage	30V

DICE/DWF SPECIFICATION

LT3680

DICE/DWF ELECTRICAL TEST LIMITS $T_A = 25^\circ\text{C}$. $V_{IN} = 10\text{V}$, unless otherwise noted.

PARAMETER	CONDITIONS	MIN	MAX	UNITS
Quiescent Current from V_{IN}	$V_{RUN/SS} = 0.2\text{V}$		0.5	μA
	$V_{BD} = 0$, Not Switching		160	μA
Quiescent Current from BD	$V_{RUN/SS} = 0.2\text{V}$		0.5	μA
	$V_{BD} = 0$, Not Switching		5	μA
Minimum Bias Voltage (BD Pin)			3	V
Feedback Voltage		780	800	mV
FB Voltage Line Regulation	$4\text{V} < V_{IN} < 36\text{V}$		0.01	%/V
Switching Frequency	$R_T = 8.66\text{k}$	2.2	2.7	MHz
	$R_T = 29.4\text{k}$	1.0	1.25	MHz
	$R_T = 187\text{k}$	200	260	kHz
Boost Schottky Reverse Leakage	$V_{BOOST} = 10\text{V}$, $V_{BD} = 0\text{V}$		2	μA
BOOST Pin Current	$I_{SW} = 1\text{A}$		50	mA
RUN/SS Pin Current	$V_{RUN/SS} = 2.5\text{V}$		8	μA
RUN/SS Input Voltage High			2.5	V
RUN/SS Input Voltage Low		0.2		V
PG Leakage	$V_{PG} = 5\text{V}$		1	μA
SYNC Low Threshold		0.5		V
SYNC High Threshold			0.7	μA

Note 1: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

Wafer level testing is performed per the indicated specifications for dice. Considerable differences in performance can often be observed for dice versus packaged units due to the influences of packaging and assembly on certain devices and/or parameters. Please consult factory for more information on dice performance and lot qualifications via lot sampling test procedures.

Dice data sheet subject to change. Please consult factory for current revision in production.